

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6534658

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
NEVIL N. GAJERA	02/03/2021
KARTHIK SARPATWARI	02/03/2021
ZHONGYUAN LU	02/03/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MICRON TECHNOLOGY, INC.
<b>Street Address:</b>	8000 SOUTH FEDERAL WAY
<b>City:</b>	BOISE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83707
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17167618
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	312-456-8400
<b>Email:</b>	gtipmail@gtlaw.com
<b>Correspondent Name:</b>	GREENBERG TRAURIG, LLP (SV)
<b>Address Line 1:</b>	77 WEST WACKER DRIVE, SUITE 3100
<b>Address Line 2:</b>	INTELLECTUAL PROPERTY DEPARTMENT
<b>Address Line 4:</b>	CHICAGO, ILLINOIS 60601
<b>ATTORNEY DOCKET NUMBER:</b>	120426-114400/US
<b>NAME OF SUBMITTER:</b>	WHITNEY ESCALANTI
<b>SIGNATURE:</b>	/Whitney Escalanti/
<b>DATE SIGNED:</b>	02/04/2021
<b>Total Attachments: 3</b>	
source=120426-114400_Assignments#page1.tif	
source=120426-114400_Assignments#page2.tif	
source=120426-114400_Assignments#page3.tif	

**PATENT ASSIGNMENT**

TO ALL WHOM IT MAY CONCERN, be it known that for good and valuable consideration, the receipt, sufficiency and adequacy of which are hereby acknowledged, as the below named inventor of an invention entitled:

**EVALUATION OF BACKGROUND LEAKAGE TO SELECT WRITE VOLTAGE IN  
MEMORY DEVICES**

which is described in:

- ☒ the attached application, or
- ☐ United States Patent Application Serial Number \_ filed on \_\_,

THE UNDERSIGNED does hereby:

SELL, ASSIGN AND TRANSFER to Micron Technology, Inc., a corporation organized and existing under the laws of the State of Delaware, and having a place of business at 8000 South Federal Way, Boise, ID 83707, US (hereinafter referred to as ASSIGNEE), which is desirous of acquiring the entire interest in, to and under said invention and in, to and under Letters Patent or similar legal protection to be obtained therefore in the United States and in any and all foreign countries, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the ASSIGNEE;

WARRANT AND COVENANT that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the ASSIGNEE, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the ASSIGNEE all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the ASSIGNEE shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the ASSIGNEE;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the ASSIGNEE.

<b>Legal Name of Inventor</b>	<b>Last Name</b> GAJERA	<b>First Name</b> Nevil	<b>Middle Name</b> N.
<b>Residence &amp; Citizenship</b>	<b>City</b> Meridian	<b>State &amp; Country</b> ID, US	<b>Country of Citizenship</b> US
<b>Mailing Address</b>	<b>Street</b> 3637 N Leslie Way	<b>City</b> Meridian	<b>State &amp; Country</b> ID 83646, US
<b>Signature of Inventor:</b> /Nevil N Gajera/			<b>Date:</b> 2/3/2021

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<b>Legal Name of Inventor</b>	<b>Last Name</b> SARPATWARI	<b>First Name</b> Karthik	<b>Middle Name</b>
<b>Residence &amp; Citizenship</b>	<b>City</b> Boise	<b>State &amp; Country</b> ID, US	<b>Country of Citizenship</b> IN
<b>Mailing Address</b>	<b>Street</b> 4775 S. Spotted Horse Ave	<b>City</b> Boise	<b>State &amp; Country</b> ID 83716, US
<b>Signature of Inventor:</b> /Karthik Sarpatwari/			<b>Date:</b> 02/03/2021

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THE UNDERSIGNED does hereby:

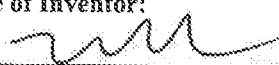
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Legal Name of Inventor	Last Name LU	First Name Zhongyuan	Middle Name
Residence & Citizenship	City Boise	State & Country ID, US	Country of Citizenship CN
Mailing Address	Street 6631 S. Kirra Way	City Boise	State & Country ID 83709, US
Signature of Inventor: // 		Date: 02/03/2021	

**PATENT**